

Title (en)

EARPHONE STORAGE CASE, WIRELESS EARPHONE, EARPHONE COMPONENTS AND INTERACTION METHOD FOR EARPHONE COMPONENTS

Title (de)

KOPFHÖRERVERWAHRUNGSGEHÄUSE, KABELLOSER KOPFHÖRER, KOPFHÖRERKOMPONENTEN UND INTERAKTIONSVERFAHREN FÜR KOPFHÖRERKOMPONENTEN

Title (fr)

BOÎTIER DE RANGEMENT D'ÉCOUTEUR, ÉCOUTEUR SANS FIL, COMPOSANTS D'ÉCOUTEUR ET PROCÉDÉ D'INTERACTION POUR COMPOSANTS D'ÉCOUTEUR

Publication

EP 4027653 A4 20230208 (EN)

Application

EP 20860100 A 20200826

Priority

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Abstract (en)

[origin: EP4027653A1] Embodiments of this application disclose a headset case, a wireless headset, a headset assembly, and a headset assembly interaction method. The headset case is configured to accommodate the wireless headset; and the headset case includes: a headset case body, a wearable structure, and a first clamping member and a second clamping member that cooperate with each other. The first clamping member is disposed in the headset case body, the second clamping member is disposed on the wearable structure, and the first clamping member and the second clamping member cooperate with each other to enable the headset case body to be detachably clamped on the wearable structure. The wearable structure is disposed in the headset case provided in embodiments of this application, so that the user can carry the headset case anywhere, and wearing comfort and accommodation convenience are improved.

IPC 8 full level

H04R 1/10 (2006.01)

CPC (source: CN EP)

A45C 11/00 (2013.01 - CN EP); **H04R 1/10** (2013.01 - CN); **H04R 1/1016** (2013.01 - EP); **H04R 1/1025** (2013.01 - CN EP); **H04R 1/1041** (2013.01 - EP); **A45C 2011/001** (2013.01 - CN EP); **H04R 2420/07** (2013.01 - EP)

Citation (search report)

- [XYI] WO 2018166486 A1 20180920 - QINGDAO HAIER JOINT STOCK CO LTD [CN], et al
- [XYI] CN 109892756 A 20190618 - 1MORE ACOUSTICS TECH CO LTD
- [XYI] CN 204231644 U 20150325 - QINGDAO GOERTEK CO LTD
- [XYI] CN 209017265 U 20190621 - GOERTEK TECH CO LTD
- [XYI] WO 2018112689 A1 20180628 - HUAWEI TECH CO LTD [CN]
- [Y] EP 2937744 A2 20151028 - SAMSUNG ELECTRONICS CO LTD [KR]
- See references of WO 2021043044A1

Designated contracting state (EPC)

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